

SS-224 R2 AHA 11/06/01

Multilayer Ferrite Chip Bead Array **Type FBA**

ISO 9002

1. Scope of Application

Noise suppression in signal I/O lines and other circuits that require multiple chip beads for noise suppression.

1.1 Applications

Computers

■ Telecommunications equipment

■ Peripherals

Data communications

2. Features

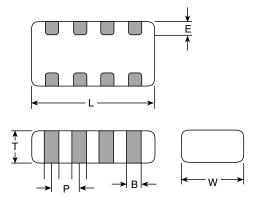
The Multilayer Ferrite Chip Bead Array retains all the features of Multilayer Ferrite Chip Beads. In addition, it provides multiple circuits in a single package, which reduce the required land space on PCB and reduce the cost for assembly.

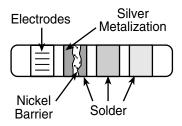
3. Dimension and Structure

Table 1

L Inch (mm)	W Inch (mm)	T Inch (mm)	B Inch (mm)	P Inch (mm)	E Inch (mm)
0.126 ± 0.008	0.063 ± 0.008	0.031± 0.008	0.014 ± 0.008	0.031 ± 0.004	0.012 ± 0.008
(3.20 ± 0.20)	(1.60 ± 0.20)	(0.80 ± 0.20)	(0.35 ± 0.20)	(0.80 ± 0.10)	(0.30 ± 0.20)

3.1 Dimensions





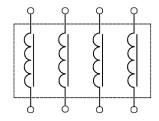
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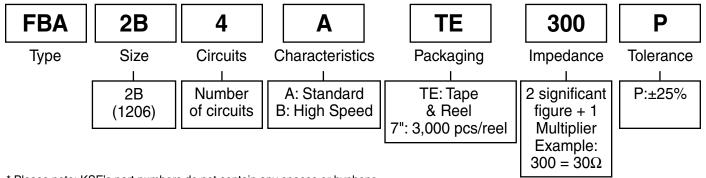
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3. Dimension and Structure

3.2 Circuit



4. Ordering and Specifying Information*



 $[\]ensuremath{^{\star}}$ Please note: KSE's part numbers do not contain any spaces or hyphens.

5. Standard Applications

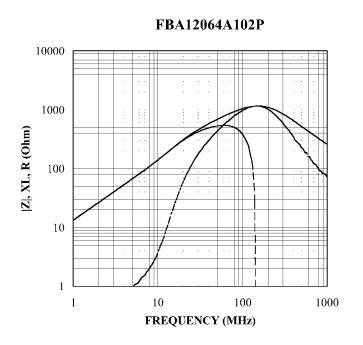
Ordering Code	Impedance @ 100MHz Ω	$\begin{array}{c} \textbf{Maximum DC} \\ \textbf{Resistance} \\ \Omega \end{array}$	Allowable DC Current (mA)	Operating Temperature
FBA2B4ATE300P	30	0.1	200	
FBA2B4ATE600P	60	0.25	200	
FBA2B4ATE121P	120	0.3	150	
FBA2B4ATE221P	220	0.3	150	
FBA2B4ATE301P	300	0.4	250	-55°C
FBA2B4ATE601P	600	0.5	100	to
FBA2B4ATE102P	1,000	0.7	50	125°C
FBA2B4BTE121P	120	0.5	100	
FBA2B4BTE221P	220	0.55	100	
FBA2B4BTE471P	470	0.55	100	
FBA2B4BTE601P	600	0.65	100	

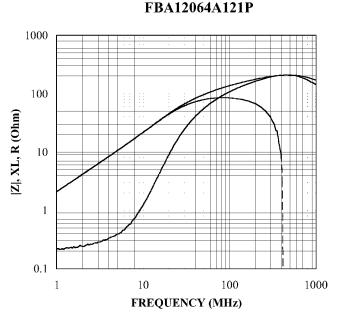
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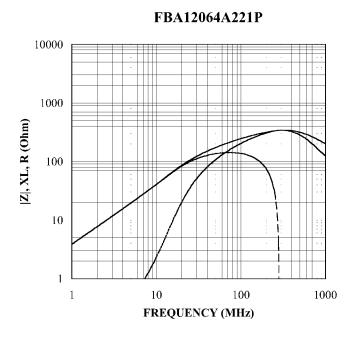


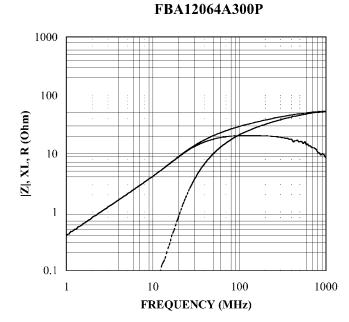
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6. Graphs*









* ----- |Z| ----- XL

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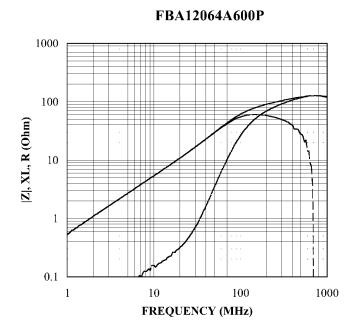
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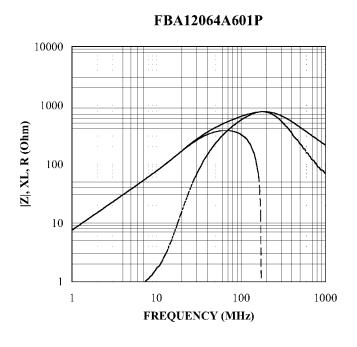
6. Graphs* (continued)

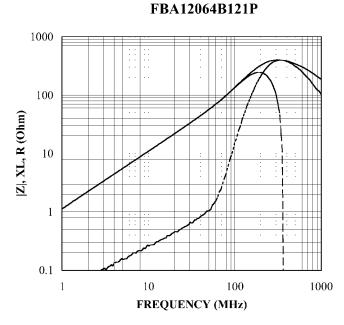
FBA12064A301P

10000
1000
1000
1000
100
100
1000
1000

FREQUENCY (MHz)







* ----- |Z| ----- XL

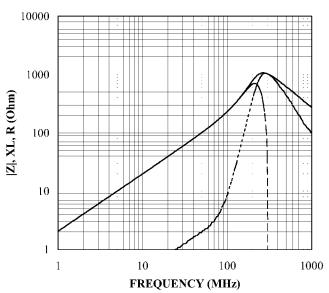
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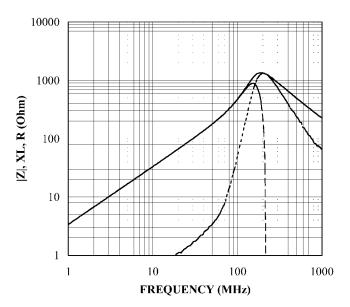
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6. Graphs* (continued)

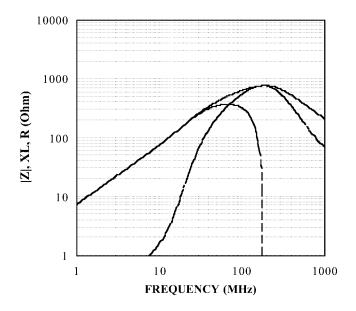
FBA12064B221P



FBA12064B471P



FBA2B4A601





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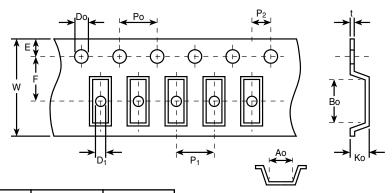
6. Packaging Specifications

KOA's multilayer components are provided on tape-and-reel for use in pick-and-place machines. The reel size is 7 inch.

7. Dimensions - inches (mm)

Таре	Ao	Во	Ко	
1206	0.071±0.002	0.138±0.002	0.048±0.002	
(3216)	(1.8±0.1)	(3.5±0.1)	(1.2±0.1)	

Таре	E	F	W	
	0.069±0.004 (1.75±0.10)		0.318±0.002 (8.1±0.1)	



Tape	P ₁	Ро	P_2	Do	D ₁	t
1206 (3216)				0.059±0.004 (1.5+0.1/-0.0)		

8. Chip Quantities Per Reel

Chip Size	Parts on 7 inch (178mm) Reel		
2B (1206)	3,000		

9. Characteristics

Item	Requirement	Conditions	
Operating Temperature	-55°C ~ +125°C		
Storage Temperature	40°C @ 70% Humidity	Sealed plastic bags with desiccant shall be used to reduce the potential of oxidation on the terminations during storage.	
Resistance to Solder Heat	Change in Impedance: Relative to value before test ±20%. Appearance: There shall be no cracking Solder Coverage: More than 75% of the terminal electrode shall be covered with solder.	Flux: 5-10 sec dip After Flux: Air dry for 15 sec Preheat: 150°C ±10°C Preheat Time: 60 sec Solder Temp: 260°C ±5°C Dip Time: 10 ±1 sec	

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9. Characteristics (continued)

Item	Requirement	Conditions		
Solderability	Solder Coverage: More than 95% of the termination shall be covered with solder.	Flux: 5-10 sec dip After Flux: Air dry for 15 sec Solder Temp: 245°C ±5°C Dip Time: 5 ±0.5 sec		
Leach Resistance	Appearance: There shall be no visible signs of physical or mechanical damage (i.e. no cracks) Terminations: Termination must not be leached away for more than 5%.	The bead shall be subjected to the following 5 steps for the period of time shown below. The 5 steps constitute one (1) rotation. 4 rotations shall be carried out. 1) Flux: 5-10 sec 2) After Flux: Air dry for 15 sec 3) Solder Temp: 230°C ±5°C 4) Dip Time: 5 ±0.5 sec 5) Cool: Air cool for 60 seconds		
Insulation Resistance	Insulation Resistance: Min 1G ohms			
Solvent Resistance	Change in Impedance: Relative to value before test ±10%.	Cleaning by: Washer: Ultrasonic washer (100W) Solvent: Isopropyl alcohol Time: 3 minutes		
Terminal Strength (hanging test)	Appearance: The terminal electrode shall not break off, nor shall there be damage to the body.	Type W(kgf) Time 1206 1.5 30 sec ±2 sec		
Terminal Strength (push test)	Appearance: There shall be no evidence of mechanical degradations to terminals or body.	Type W(kgf) Time 1206 2.3 60 sec		
Bending Strength	Appearance: There shall be no physical or mechanical damage Impedance: Relative to initial value before test ±10%	Board: 90x40x1.6mm Bend: 1mm Time: 5 sec		
Mechanical Shock	Appearance: There shall be no physical or mechanical damage Impedance: Relative to initial value before test ±10%	Force: 50G Time: 11 msec There shall be 3 shocks in each of 6 directions (18 shocks total).		
Vibration	Impedance: Relative to initial value ±10%	Only endurance conditioning by sweeping shall be made. The entire frequency range from 10-2,000Hz and return to 10Hz in 20 minutes (this shall constitute one cycle). Amplitude: 1.5mm The test shall have a 15G peak and shall be applied for a period of 4 hours (12 cycles) in each of 3 mutually perpendicular directions (a total of 36 cycles within a total of 12 hours).		

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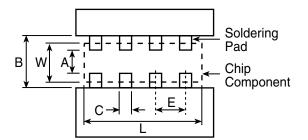


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9. Characteristics (continued)

Item	Requirement	Conditions		
Thermal Shock	Appearance: There shall be no physical or mechanical damage. Impedance: Relative to initial value ±20%. DCR: The DCR shall not exceed initial specified value. Testing of the parts will be made at 0 hours, 250 hours and 500 hours. Before testing the parts shall be allowed to cool to room temperature for 24 hours.	Step Temperature 1-start -40°C ±2°C 2-hold -40°C ±2°C 30 min ±5 min 3-transfer — 0.5 min max. 4-hold +105°C ±2°C 30 min ±5 min 5-transfer — 0.5 min max. Steps 1 thru 5 constitute one complete cycle and the test shall consist of a total of 500 cycles.		
Load Humidity	Appearance: There shall be no physical or mechanical damage Impedance: Relative to initial value ±15% Measurements shall be taken at 0 hours, 250 hours, 500 hours and 1,000 hours and shall meet the conditions stated above.	Temperature: 85°C ±2°C Relative Humidity: 85% Time: 1,000 hours total Apply: 100% rated current		
Life Test	Appearance: There shall be no physical or mechanical damage Impedance: Relative to initial value ±15% Measurements shall be taken at 0 hours, 250 hours, 500 hours and 1,000 hours and shall meet the conditions stated above.	Temperature: 85°C ±2°C Time: 1,000 hours total Apply: 100% rated current		

10. Recommended PC Board Land Patterns - inches (mm)



Chip	Component Size			_		_
Size	L	W	A	В	С	
1206 (3216)	.020 (0.5 x n)	.039 (1.0)	.020 (0.5)	.059 (1.5)	.012 (0.3)	.020 (0.5)

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